

**REMARKS**

Claims 1, 2, 9-15 and 21 are pending in this application. By this Amendment, claim 9 is amended and 21 is added. No new matter is added by these amendments as support can be found in at least paragraphs [0054], [0057], [0077], [0078] and Fig. 12(b) of Applicants' disclosure. Reconsideration of the application based on the above amendments and the following remarks is respectfully requested.

The Office Action rejects claims 6, 7, 13, 14, 18 and 19 under 35 U.S.C. §112, second paragraph, as being indefinite. The cancellation of claim 3 renders this rejection moot.

The Office Action rejects claims 3-5, 8, 16, 17 and 20 under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 3,459,391 to Haynos; rejects claims 3-15 under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 4,210,462 to Tourneux; rejects claims 6, 7 and 9-15 under 35 U.S.C. §103(a) as being unpatentable over Haynos in view of Tourneux; rejects claims 16-20 under 35 U.S.C. §103(a) as being unpatentable over Tourneux in view of Haynos; rejects claims 3-6, 8-10, 12, 13 and 15 under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 5,498,297 to O'Neill; rejects claims 7, 11 and 14 under 35 U.S.C. §103(a) as being unpatentable over O'Neill in view of Tourneux; rejects claims 16-18 and 20 under 35 U.S.C. §103(a) as being unpatentable over O'Neill in view of Haynos; and rejects claim 19 under 35 U.S.C. §103(a) as being unpatentable over O'Neill in view of Haynos, and further in view of Tourneux. Applicants respectfully traverse these rejections.

The cancellation of claims 3-8 and 16-20 renders the rejection of these claims moot.

The Office Action asserts that Haynos teaches all of the features recited in the pending claims. However, Haynos does not teach, nor would it have suggested, that a lower surface of the semiconductor structure is located below a surface of said heat dissipating layer. Instead, Haynos teaches, as illustrated in Fig. 3, that the lower end of the interconnector 16, connected

to the solar cell 12, is located below the upper surface of the heat dissipating layer 23. This is in direct contrast to the subject matter of the amended claims, as illustrated in Fig. 12B.

With respect to the Tourneux reference, the Office Action improperly identifies the adhesive layer 19 as being one of two layers of a heat dissipating plate, *i.e.*, a bottom adhesive and inset plate. However, based on the assertions of the Office Action, and the Advisory Action, if one were to concede that Tourneux at least suggests two layers, then the second layer, as recited in the pending claims, corresponds to a inset plate. However, Tourneux does not teach, nor would it have suggested, that the inset plate has the properties, as recited in the pending claims, that "said second layer being formed of a non-thermoplastic material a modulus of elasticity or coefficient of viscosity of which is lowered below that of said first layer during a rise of a temperature of the non-thermoplastic material within a predetermined range in the process of heating of the material to cure the non-thermoplastic material."

The subject matter of the pending claims recites that the first layer and the second layer of the heat dissipating layer have different properties. Selection of the non-thermoplastic material considers at least the manufacturing process and the high temperature conditions experienced in a photovoltaic electric generator. That is, if the second layer temporarily softens in the predetermined temperature range during manufacturing, it non-reversibly hardens and does not soften again even under the further temperature rise. As such, upon the manufacturing of the photovoltaic electric generator, by maintaining the insulating characteristic between the base plate and the solar cell, the solar cell can be disposed as close as possible to the base plate. Further, during usage under high temperature conditions, after manufacturing the solar cell, the cell is held in the state where the second layer is softened, so that the thermal expansion influence of the base plate to the solar cell can be minimized, thereby preventing the solar cell from being damaged. During this period, the first layer acts as the shock absorber.

Regarding the O'Neill reference, the Office Action asserts that O'Neill teaches all of the features recited in the subject matter of canceled claim 3, which has been incorporated into pending amended claim 9, and claim 9. This is incorrect for the following reasons.

First, the Office Action asserts that it would have been obvious to one skilled in the art that part of the assembly 6 of O'Neill will be "embedded" within the lower pressure sensitive layers 42 because of the pressure exerted from the upper cell package 6. However, O'Neill does not teach, nor would it have suggested, "such that side surfaces thereof is covered by said heat dissipating layer," as positively recited in amended claim 9. Instead, the Office Action asserts that O'Neill makes an indentation into the lower pressure sensitive layer, and not that it covers the sides.

Second, O'Neill does not teach, as discussed above with respect to Tourneux, that "said second layer being formed of a non-thermoplastic material a modulus of elasticity or coefficient of viscosity of which is lowered below that of said first layer during a rise of a temperature of the non-thermoplastic material within a predetermined range in the process of heating of the material to cure the non-thermoplastic material," as positively recited in pending claim 9.

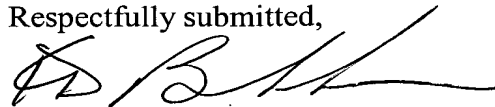
For at least the above reasons, Haynos, Tourneux and/or O'Neill, in any permissible combination, cannot reasonably be considered to teach, or to have suggested, the combinations of all of the features recited in at least independent claim 9. Further, claims 1, 2 and 10-15 would also not have been suggested by the applied prior art references for at least the respective dependence of these claims on allowable independent claim 9, as well as for the separately patentable subject matter that each of these claims recites.

Accordingly, reconsideration and withdrawal of the rejections of claims 1, 2 and 9-15 under 35 U.S.C. §102 and §103 as being unpatentable over the combination of applied prior art references are respectfully requested.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1, 2, 9-15 and 21 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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Attachments:

Request for Continued Examination  
Petition for Extension of Time.

Date: January 24, 2008

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